

Product Change Notice

Issue Date: 05-August-2022

Change Description:

1pc thermal pad instead of 2pc stacked thermal pad

Parts Affected:

AFBR-59E4APZ-HT

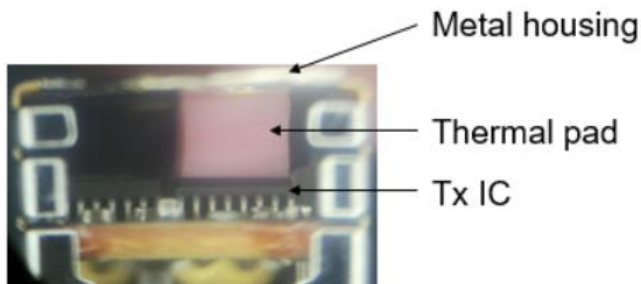
Description and Extent of Change:

Current situation:

- Two pieces of thermal pads are mounted stacked between the Tx IC and housing to move heat away from Tx IC package to the housing.

Change:

- Use of a single piece thermal pad (4.5mm in height) of the same material, see picture below:



Reasons for Change:

More effective thermal transfer from Tx IC to device housing and improved assembly process.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

No change on Fit, Form, Function, Quality or Reliability.

Effective Date of Change:

Product shipments using this change will begin after 12/05/2022 (WW2250). Timing of shipment of the changed part will vary depending on qualification completion, customer demand, and inventory levels.

Qualification Data:

Qualification samples are available

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please acknowledge the receipt of the notice within 30 days of delivery. Lack of acknowledgement within 30 days constitutes acceptance of the change per JEDEC J-STD-046.